



Circuit Editing Pricing Table

¹Turnaround time 5-6 business days

²Actual pricing may vary depending on sample details

³For services not listed, please contact us for pricing

Service Name	Service Description	Unit	Price
Decapsulation-C1	Plastic package decap to check top of mono die (plastic package or Multi Chip Package (MCP))	Each	\$60
Decapsulation-C2	Laser decap	Each	\$100
Decapsulation-C3	Special decap to remove bottom substrate of MCP, Ball Grid Array (BGA) type	Each	\$120
Decapsulation-C4	Advanced decap to remove bottom substrate of MCP, BGA type	Each	\$240
FIB Circuit Modification	Cost per hour for circuit modification	Hour	\$250